# imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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### Switch-Mode **Power Rectifier**

This ultrafast rectifier in the dual flag SO-8 flat lead package offers designers a unique degree of versatility and design freedom. The two devices are electrically independent and can be used separately, as common cathode, as common anode or in series as a function of board level layout. The exposed pad design provides low thermal resistance. The clip attach design creates a package with very efficient die size to board area ratio. While thermal performance is nearly the same as the DPAK package height and board footprint are less than half.

#### Features

- New Package Provides Capability of Inspection and Probe After **Board Mounting**
- Low Forward Voltage Drop
- 175°C Operating Junction Temperature
- NRV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb–Free and Halide–Free Devices

#### **Mechanical Characteristics:**

- Case: Epoxy, Molded
- Epoxy Meets Flammability Rating UL 94–0 @ 0.125 in.
- Lead Finish: 100% Matte Sn (Tin)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL 1 Requirements

#### **Applications**

- Excellent Alternative to DPAK in Space-Constrained Automotive Applications
- Output Rectification in Switching Power Supplies
- Freewheeling Diode used with Inductive Loads



#### **ON Semiconductor®**

www.onsemi.com

### **ULTRAFAST RECTIFIER** 4 AMPERES (2x2), 200 VOLTS





1	A1 I	C1 C1	յ C1
DFN8 5x6	NCI	HP420D	յ C1
(SO8FL)	A2 r	HP420D	C2
CASE 506BT	NC r	AYWZZ	
		C2 C2	<u> </u>
	Specific [	Jourine Code	

HP420D = Specific Device Code Α = Assembly Location

= Year

Υ

= Work Week w ZZ = Lot Traceability

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NRVHP420MFDT1G	DFN8 (Pb–Free)	1500 / Tape & Reel
NRVHP420MFDT3G	DFN8 (Pb–Free)	5000 / Tape & Reel
NRVHP420MFDWFT1G	DFN8 (Pb–Free)	1500 / Tape & Reel
NRVHP420MFDWFT3G	DFN8 (Pb–Free)	5000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

#### MAXIMUM RATINGS (per diode unless noted)

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	200	V
Average Rectified Forward Current (Rated $V_R$ , $T_C = 167^{\circ}C$ )	I <sub>F(AV)</sub>	2.0	A
Peak Repetitive Forward Current, (Rated $V_R$ , Square Wave, 20 kHz, $T_C = 165^{\circ}C$ )	I <sub>FRM</sub>	4.0	A
Non–Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I <sub>FSM</sub>	40	A
Storage Temperature Range	T <sub>stg</sub>	-65 to +175	°C
Operating Junction Temperature	ТJ	-55 to +175	°C
Unclamped Inductive Switching Energy (10 mH Inductor, Non-repetitive)	E <sub>AS</sub>	10	mJ
ESD Rating (Human Body Model)		2	
ESD Rating (Machine Model)		M4	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS (per diode unless noted)

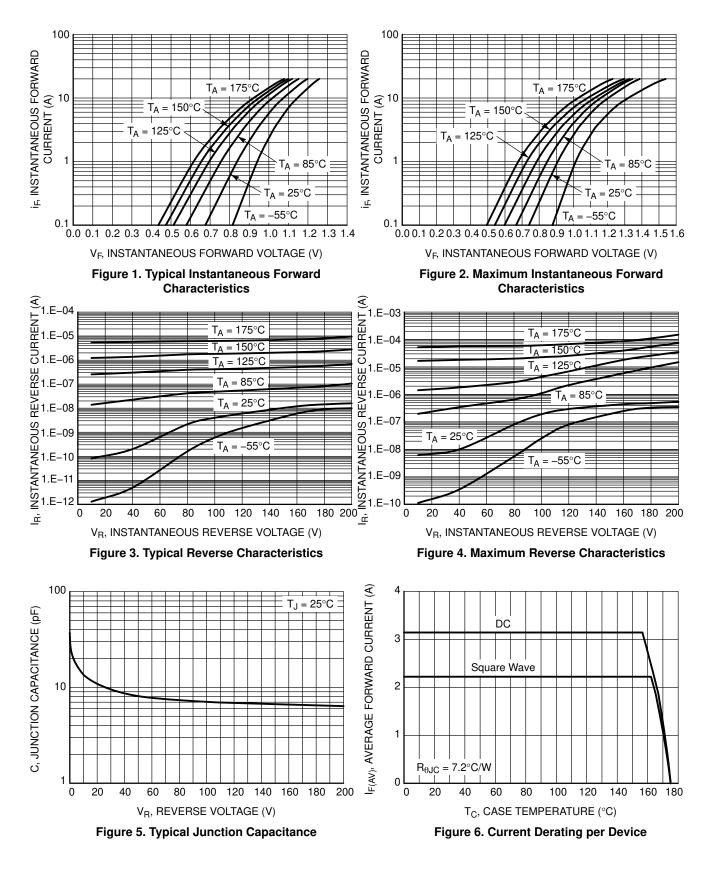
Characteristic	Symbol	Тур	Max	Unit
Thermal Resistance, Junction-to-Case, Steady State (Assumes 600 mm <sup>2</sup> 1 oz. copper bond pad, on a FR4 board)	R <sub>θJC</sub>	-	7.2	°C/W
	-	-	-	-

ELECTRICAL CHARACTERISTICS (per diode unless noted)

$ \begin{array}{l} \mbox{Instantaneous Forward Voltage (Note 1)} \\ (i_F = 3.0 \mbox{ Amps, } T_J = 125^{\circ}\mbox{C}) \\ (i_F = 3.0 \mbox{ Amps, } T_J = 25^{\circ}\mbox{C}) \\ (i_F = 6.0 \mbox{ Amps, } T_J = 125^{\circ}\mbox{C}) \\ (i_F = 6.0 \mbox{ Amps, } T_J = 25^{\circ}\mbox{C}) \\ \end{array} $	VF	0.76 0.89 0.86 0.96	0.85 1.0 0.95 1.10	V
Instantaneous Reverse Current (Note 1) (Rated dc Voltage, $T_J = 125^{\circ}C$ ) (Rated dc Voltage, $T_J = 25^{\circ}C$ )	iR	1.00 0.03	35 0.5	μΑ
Reverse Recovery Time I <sub>F</sub> = 3.0 A, V <sub>R</sub> = 30 V, dl/dt = 50 A/ $\mu$ s, T <sub>J</sub> = 25°C	t <sub>rr</sub>	20	30	ns
Reverse Recovery Time I <sub>F</sub> = 3.0 A, V <sub>R</sub> = 30 V, dl/dt = 50 A/ $\mu$ s, T <sub>J</sub> = 125°C	t <sub>rr</sub>	23	40	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 1. Pulse Test: Pulse Width =  $300 \ \mu$ s, Duty Cycle  $\leq 2.0\%$ .

#### **TYPICAL CHARACTERISTICS**



#### **TYPICAL CHARACTERISTICS**

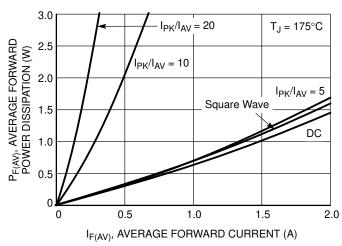


Figure 7. Forward Power Dissipation

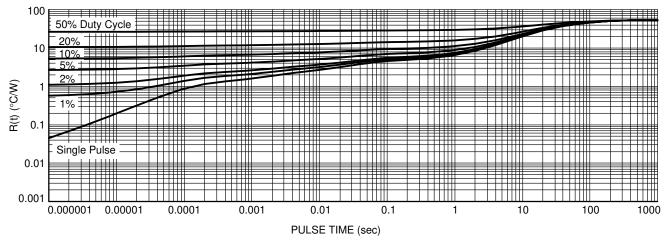
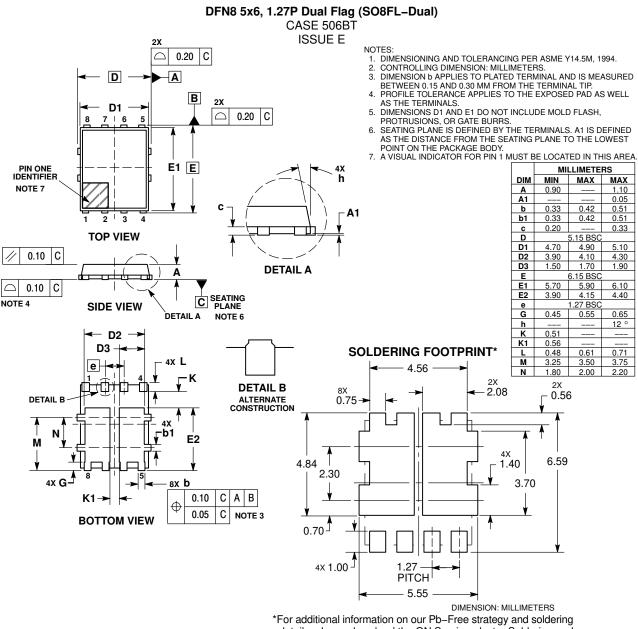


Figure 8. Typical Thermal Characteristics

#### PACKAGE DIMENSIONS



details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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